



Electronic Filing System (EFS) Data  
Electronic Patent Application Submission  
USPTO Use Only

EFS ID: 59495  
Application ID: 10608404  
Title of Invention: METHOD AND COMPOSITION  
FOR POLISHING A SUBSTRATE  
First Named Inventor: FENG LIU  
Domestic/Foreign Application: Domestic Application  
Filing Date: 2003-06-26  
Effective Receipt Date: 2004-04-22  
Submission Type: Information Disclosure  
Statement  
Filing Type:  
Confirmation number: 7966  
Attorney Docket Number: AMAT5699P3  
  
Total Fees Authorized: 180.0  
Payment Category: Deposit Account  
Deposit Account Number: 200782  
Deposit Account Name: BRIAN K. HRNA  
Access Code: \*\*\*\*  
RAM Payment Status: RAM success  
RAM User ID: EFSPROD  
RAM Accounting Date: 2004-04-22  
RAM Sequence Number: 17




Digital Certificate Holder: cn=Brian K. Hrna,ou=Registered Attorneys,ou=Patent and Trademark  
Office,ou=Department of Commerce,o=U.S. Government,c=US  
Certificate Message Digest: 94a324f95318cf1c8cb18de1fd0488dc6887e911





# TRANSMITTAL

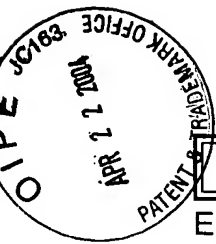
Electronic Version v1.1  
Stylesheet Version v1.1.0

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<p>I hereby certify that the use of this system is for OFFICIAL correspondence between patent applicants or their representatives and the USPTO. Fraudulent or other use besides the filing of official correspondence by authorized parties is strictly prohibited, and subject to a fine and/or imprisonment under applicable law.</p> <p>I, the undersigned, certify that I have viewed a display of document(s) being electronically submitted to the United States Patent and Trademark Office, using either the USPTO provided style sheet or software, and that this is the document(s) I intend for initiation or further prosecution of a patent application noted in the submission. This document(s) will become part of the official electronic record at the USPTO.</p>																
<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>BRIAN K. HRNA Registered Number: 41,852</td><td>[BRIAN K. HRNA]</td><td>Attorney</td></tr></tbody></table>			Submitted by:	Elec. Sign.	Sign. Capacity	BRIAN K. HRNA Registered Number: 41,852	[BRIAN K. HRNA]	Attorney								
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## Comments



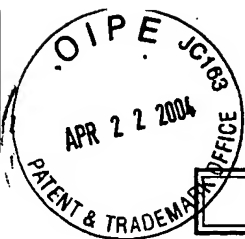


## FEE TRANSMITTAL

Electronic Version v08  
Stylesheet Version v08.0

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Application Number: 10/608404 											
Date: 2003-06-26											
First Named Applicant: FENG Q. LIU											
Attorney Docket Number: AMAT5699P3											
Art Unit: 1765											
<b>TOTAL FEE AUTHORIZED \$180</b>											
Patent fees are subject to annual revisions on or about October 1st of each year.											
<b>BASIC FILING FEE</b>											
<table border="1"><thead><tr><th>Fee Description</th><th>Fee Code</th><th>Amount \$</th><th>Fee Paid \$</th></tr></thead><tbody><tr><td>Submission Of Information Disclosure Stmt Fee</td><td>1806</td><td>180</td><td>180</td></tr></tbody></table>				Fee Description	Fee Code	Amount \$	Fee Paid \$	Submission Of Information Disclosure Stmt Fee	1806	180	180
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Submission Of Information Disclosure Stmt Fee	1806	180	180								
<b>AUTHORIZED BILLING INFORMATION</b>											
The commissioner is hereby authorized to charge indicated fees and credit any overpayments to:											
Deposit account number: 200782											
Access Code *****											
Deposit name: MOSER PATTERSON SHERIDAN											
Deposit authorized name: BRIAN K. HRNA											
Signature: /BRIAN K. HRNA/											
Date (YYYYMMDD): 2004-04-22											



**FEE TRANSMITTAL**

Electronic Version v08

Stylesheet Version v08.0

<b>Title of Invention</b>	<b>METHOD AND COMPOSITION FOR POLISHING A SUBSTRATE</b>										
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## ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of  
Invention

METHOD AND COMPOSITION FOR POLISHING A  
SUBSTRATE

Application Number: 10/608404



Confirmation Number: 7966

First Named Applicant: FENG LIU

Attorney Docket Number: AMAT5699P3

Art Unit: 1765

Search string: ( 6001730 or 5897375 or 5880003 or 5846882  
or 5783489 or 5770095 or 5407526 or 5391258  
or 5340370 or 5209816 or 5114548 or 4992135  
or 4934102 or 4793895 or 5543032 or  
20030170091 or 20030153184 or 20030136055  
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20030073386 or 20020139055 or 20020096659  
or 20020088709 or 20020070126 or  
20020016272 or 20010024878 or  
20010042690 ).pn.

### US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	6001730	1999-12-14	Farkas, et al.			
	2	5897375	1999-04-27	Watts, et al.			
	3	5880003	1999-03-09	Hayashi			
	4	5846882	1998-12-08	Birang			
	5	5783489	1998-07-21	Kaufman, et al.			
	6	5770095	1998-06-23	Sasaki, et al.			
	7	5407526	1995-04-18	Danielson, et al.			
	8	5391258	1995-02-21	Branacaleoni, et al.			
	9	5340370	1994-08-23	Cadien, et al.			
	10	5209816	1993-05-11	Yu, et al.			
	11	5114548	1992-05-19	Rhoades			
	12	4992135	1991-02-12	Doan			



	13	4934102	1990-06-19	Edson
	14	4793895	1988-12-27	Kaanta, et al.
	15	5543032	1996-08-06	Datta, et al.

## US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
	1	20030170091	2003-09-11	Shomler, et al.			
	2	20030153184	2003-08-14	Wang, et al.			
	3	20030136055	2003-07-24	Li et al.			
	4	20030083214	2003-05-01	Kakizawa, et al.			
	5	20030079416	2003-05-01	Ma, et al.			
	6	20030073386	2003-04-17	Ma, et al.			
	7	20020139055	2002-10-03	Asano, et al.			
	8	20020096659	2002-07-25	Sakai, et al.			
	9	20020088709	2002-07-11	Hongo, et al.			
	10	20020070126	2002-06-13	Sato, et al.			
	11	20020016272	2002-02-07	Kakizawa, et al.			
	12	20010024878	2001-09-27	Nakamura			
	13	20010042690	2001-11-22	Talieh			

Signature

Examiner Name	Date